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(12) **United States Design Patent**
Nakamura

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(54) **SHAFT PORTION OF AN APPARATUS FOR HOLDING AND HEATING SEMICONDUCTOR WAFERS OR THE LIKE**

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(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (9) Cl.** **15-09**
(52) **U.S. Cl.** **D15/144.1**
(58) **Field of Classification Search** D15/138, D15/140, 144.1, 199; D26/51–63; 438/584, 438/689, 692; 451/288, 289, 388
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a shaft portion of an apparatus for holding and heating semiconductor wafers or the like, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a shaft portion of an apparatus for holding and heating semiconductor wafers or the like;
FIG. **2** is a front view thereof, a rear view being the same image of a front view;
FIG. **3** is a right side view thereof, a left side view being the same image of a right side view;
FIG. **4** is a bottom plan view thereof; and,
FIG. **5** is a sectional view taken vertically at the center of the portion shown by **5**—**5** in FIG. **2**.
The broken lines showing on the drawing disclosure are for illustrative purposes only and form no part of the claimed design. The lines consisting of long lines and dots indicate conceptual border lines between the claimed portions and the disclaimed portions.

1 Claim, 3 Drawing Sheets

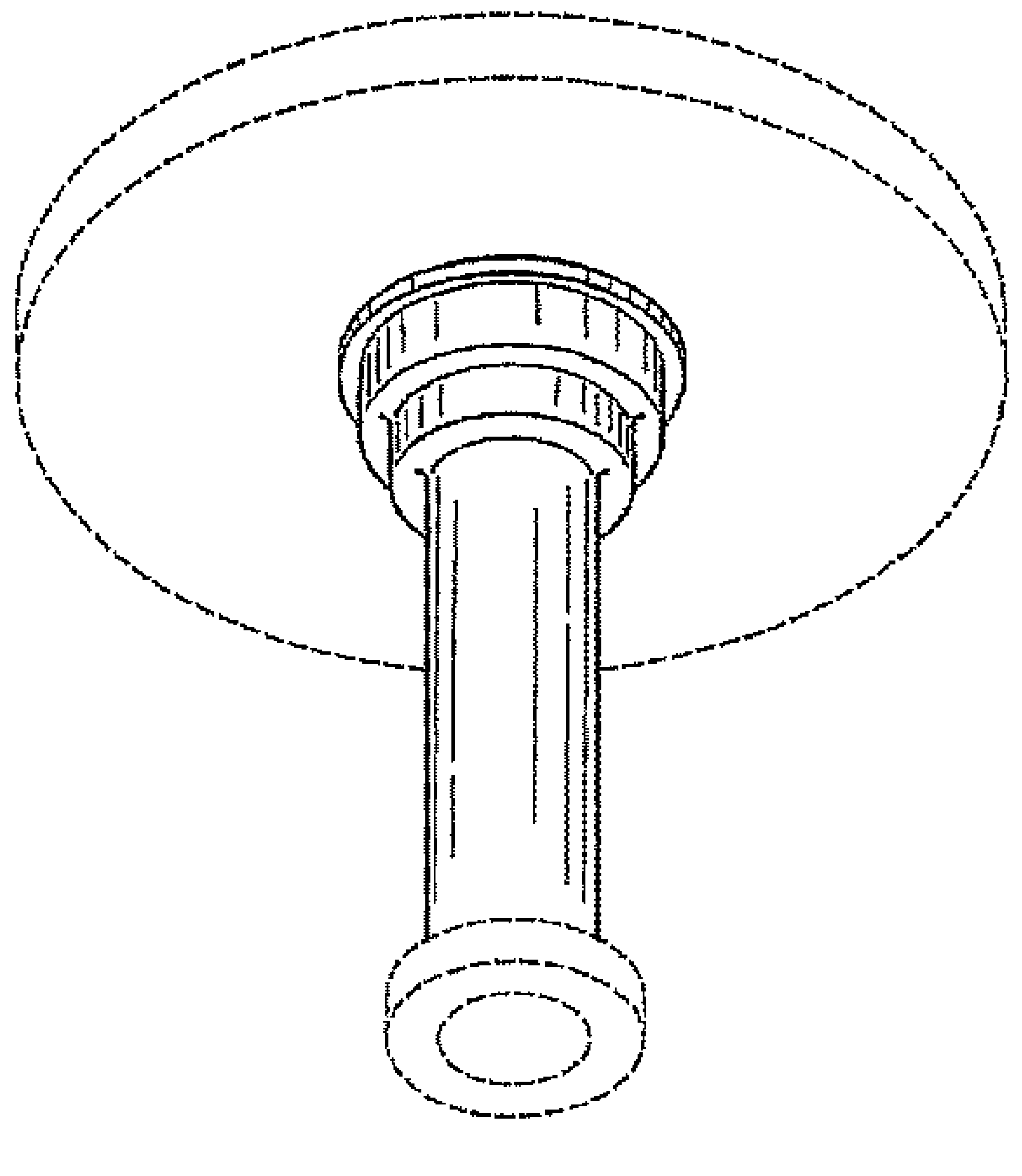

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Fig.1

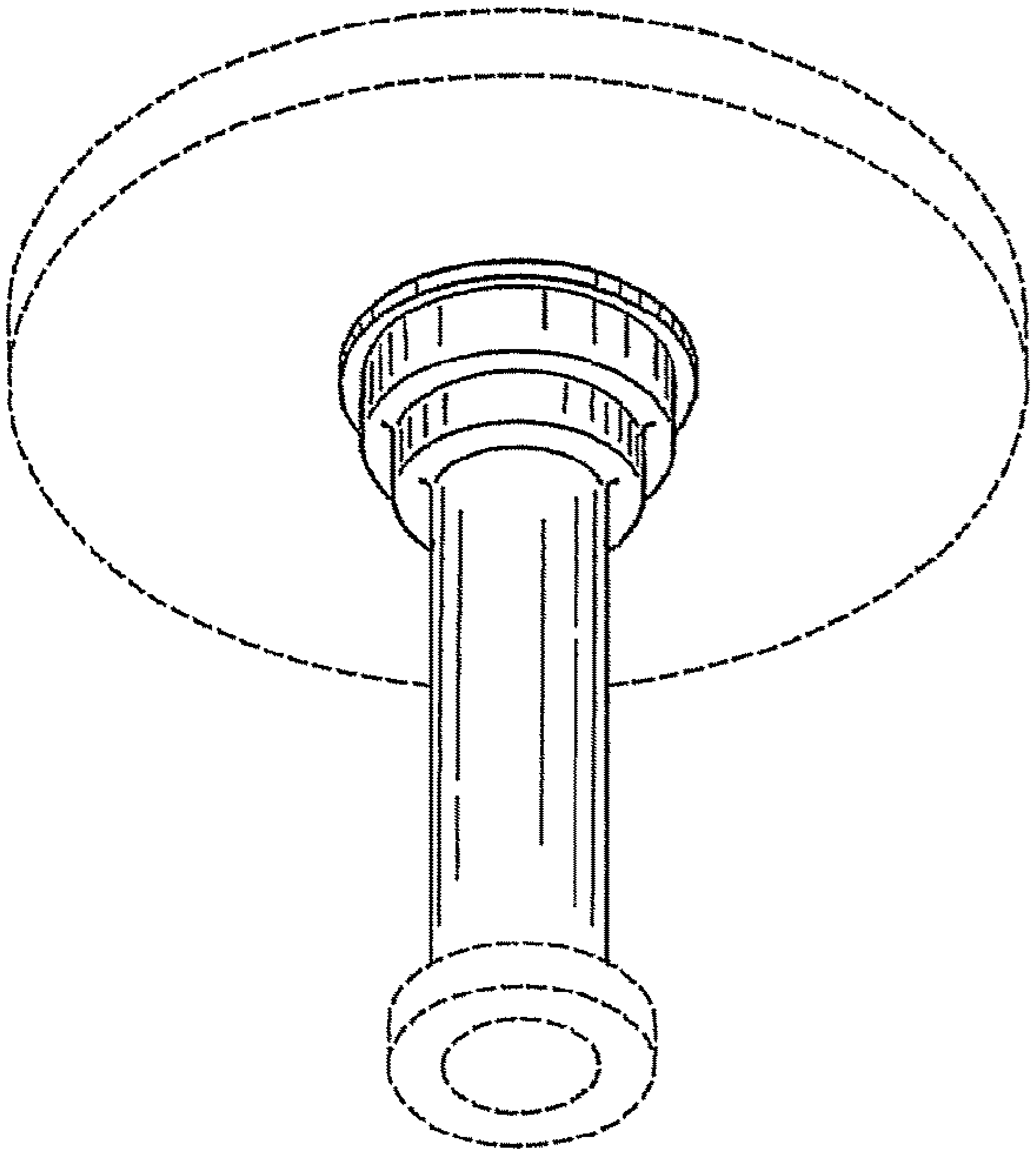

Fig.2

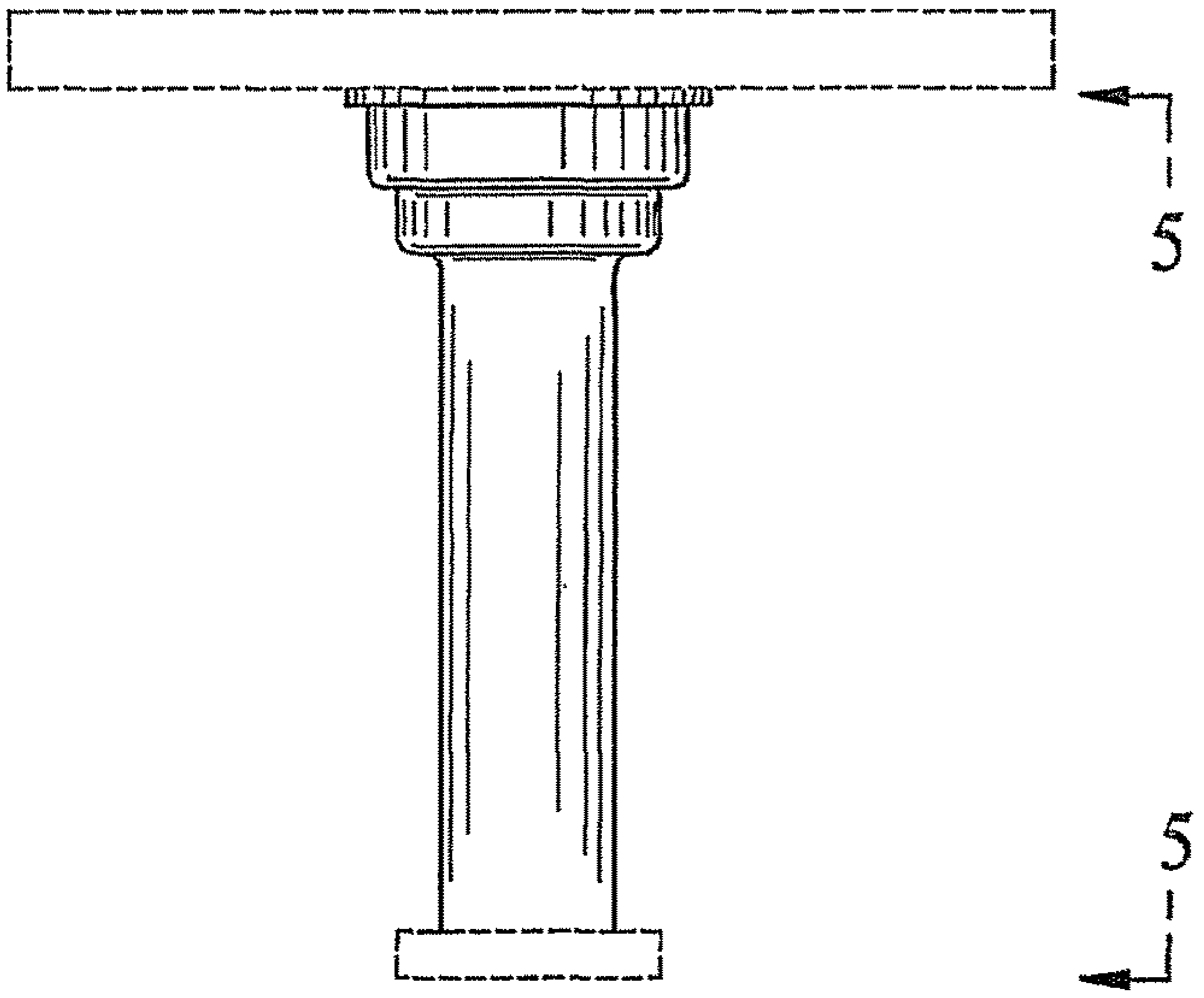

Fig.3

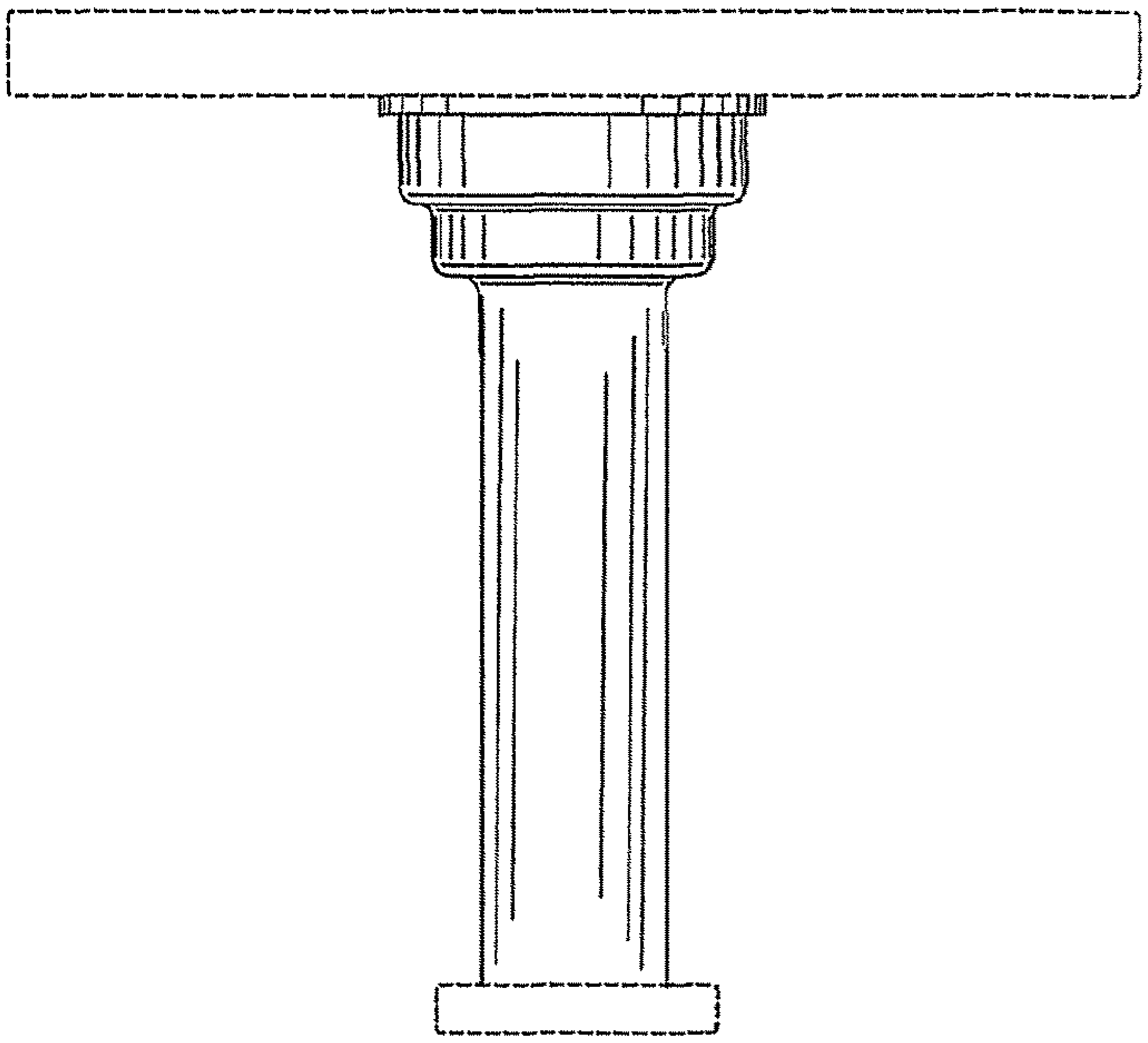

Fig.4

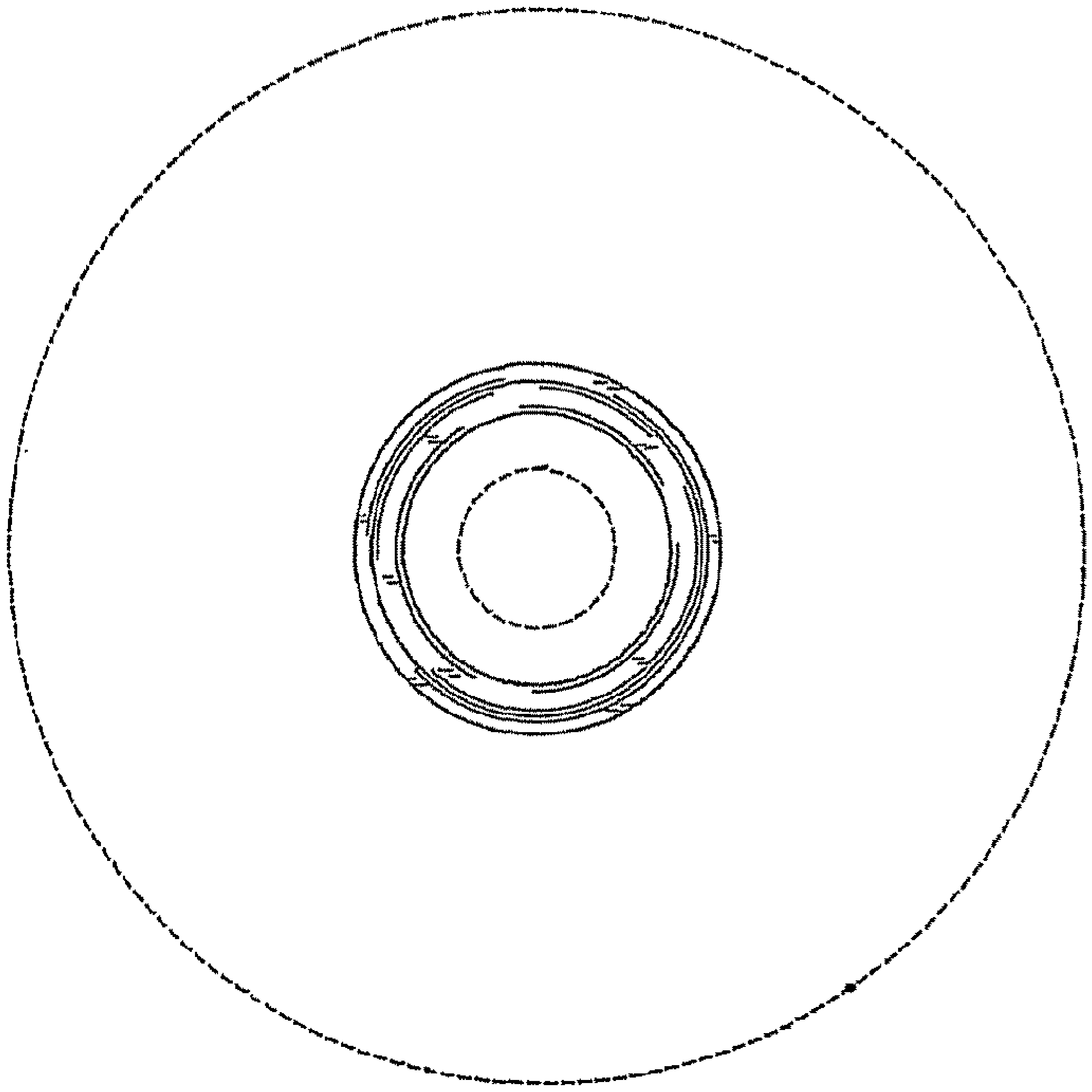

Fig.5